



October 31, 2007

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JRW

To: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Fr: Stephen B. Ackerman, Reg. No. 37,761
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject: Serial No. 09/837,007 4/18/01

M. S. LIN et al

“A Structure and Manufacturing Method of a Chip Scale
Package”

**PETITION TO ACCEPT UNINTENTIONALLY DELAYED CLAIM FOR BENEFIT,
UNDER 37 CFR 1.78(a)(3)**

Please grant the following Petition, under 37 CFR 1.78(a)(3), to accept an unintentionally delayed claim for the benefit of a prior-filed application, regarding the above-identified application for patent.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on October 31, 2007.

Stephen B. Ackerman, Reg. No. 37,761

Signature SB
Date 10/31/07

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REMARKS

Please accept the unintentionally delayed claim under 35 U.S.C. 120 for the benefit of a prior-filed application for the above-referenced patent application. A corrected benefit claim is being submitted concurrently with this Petition.

The entire delay between the date the claim was due under paragraph 37 CFR 1.78(a)(2)(ii), and the date the claim was filed, was unintentional.

The Commissioner is hereby authorized to charge the fee associated with this communication of \$1410 to our Deposit Account 19-0033, and any underpayment.

It is requested that should there be any problems with this Petition that the Examiner call the undersigned at 845 452-5863 to overcome any problems.

Respectfully submitted,



Stephen B. Ackerman, Reg. No. 37,761